# HI0603O700R-10

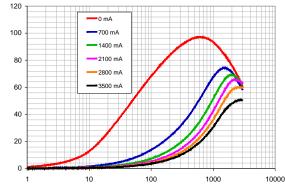
### PHYSICAL DIMENSIONS:

IMPEDANCE

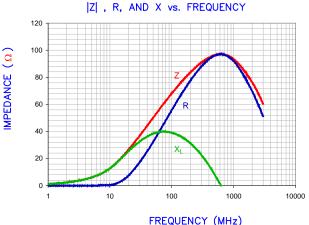
A 1.60 [.063] ± 0.15 [.006] B 0.80 [.031] ± 0.15 [.006] C 0.80 [.031] ± 0.15 [.006]

D 0.36 [.014] ± 0.15 [.006]

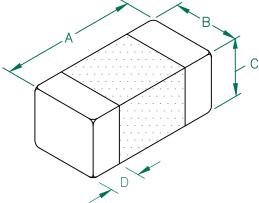
Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



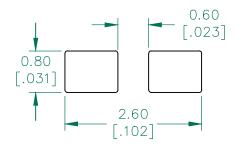
FREQUENCY (MHz)



AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 6281



#### LAND PATTERNS FOR REFLOW SOLDERING



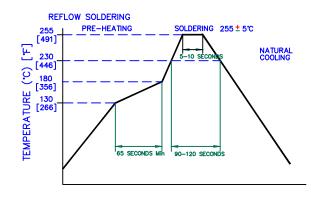
(For wave soldering, add 0.762 [.030] to this dimension)

ELECTRICAL CHARACTERISTICS:										
Z @ 100M ( Ω )	1Hz	DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current							
Nominal	70									
Minimum	53									
Maximum	88	0.022	3500 mA							

## NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMPERATURE TEMP: -40°C~+125°C. (INCLUDING SELF-HEATING)

#### RECOMMENDED SOLDERING CONDITIONS



	DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird					
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ļ					rights to design or invention are	'  ·				
ļ					reserved.					
ļ					PROJECT/PART NUMBER:	RE	:v	PART TY	PE:	DRAWN BY:
	С	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	Qυ	HI06030700R-10		С	CO-FIRE		JRK
	В	CHANGE REF#	06/03/10	JUN	DATE: 12/03/08 S	CALE:	_	_	SHEET:	
	Α	ORIGINAL DRAFT	12/03/08	JRK	CAD 4	00L 1		-	1	of 1
	REV	DESCRIPTION	DATE	INT	# HI06030700R-10-C		•	-		· '